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In the Specification:

Please replace paragraph [0007] with the following amended paragraph:

[0007] According to the present invention, an electronic package is provided that includes a circuit board having a substrate and circuitry and a surface mount device having a contact terminal. A mounting pad is formed on the circuit board. The electronic package also includes a solder joint connecting the contact terminal of the surface mount device to the mounting pad on the circuit board. The solder joint includes a reflow solder material and a plurality of stand-off members. The plurality of stand-off members provide a separation distance between the circuit board and surface mount device in the range of about 0.01 mm to 0.10 mm. Accordingly, the plurality of stand-off members provide a controlled height solder joint interconnection between a surface mount device and a circuit board so as to minimize shear fatigue which may be caused by thermal expansion and vibrations.